14.22mm (0.56INCH) DUAL DIGIT NUMERIC DISPLAY

Part Number: DC56-11CGKWA Gr

Green

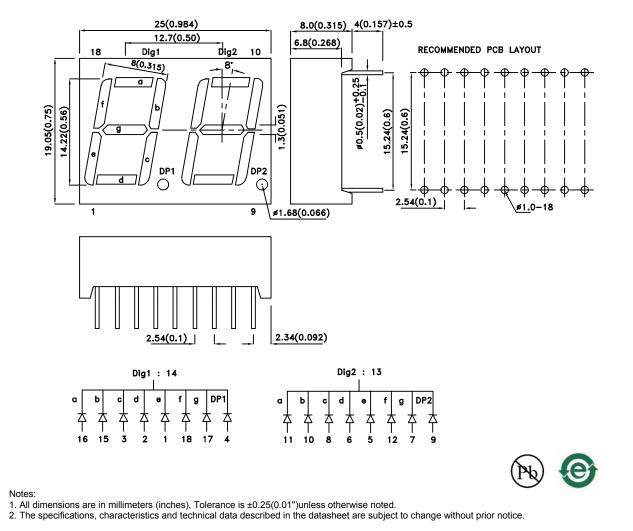
Features

- 0.56 inch digit height.
- Low current operation.
- Excellent character appearance.
- Easy mounting on P.C. boards or sockets.
- Two digit package simplifies alignments & assembly.
- Mechanically rugged.
- Standard : gray face, white segment.
- RoHS compliant.

Description

The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

Package Dimensions& Internal Circuit Diagram



SPEC NO: DSAM8359

APPROVED: WYNEC

REV NO: V.1A CHECKED: Joe Lee DATE: JAN/20/2013 DRAWN: Y.Liu PAGE: 1 OF 6 ERP: 1302000721

Selection Guide										
Part No.	Dice	Lens Type	lv (ucd) [1] @ 10mA		Description					
			Min.	Тур.						
DC56-11CGKWA	Green (AlGaInP)	White Diffused	14000	35000	Common Cathode,					
			*5600	*12000	Rt.Hand Decimal.					

Notes: 1. Luminous intensity/ luminous Flux: +/-15%. *Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	574		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Green	570		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Green	20		nm	I⊧=20mA
С	Capacitance	Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green	2.1	2.5	V	I⊧=20mA
lr	Reverse Current	Green		10	uA	

Notes:

1.Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

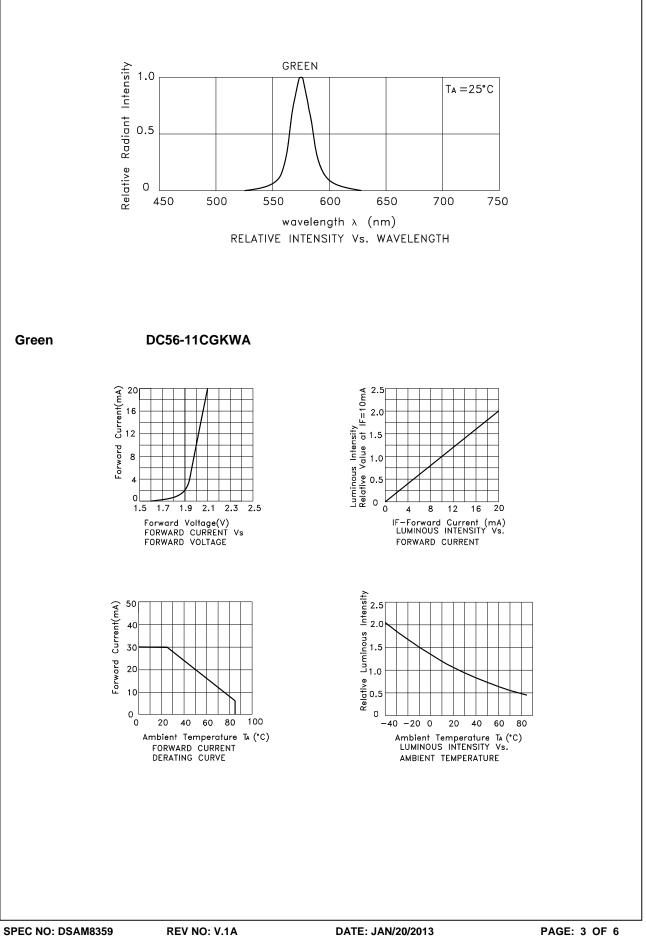
3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

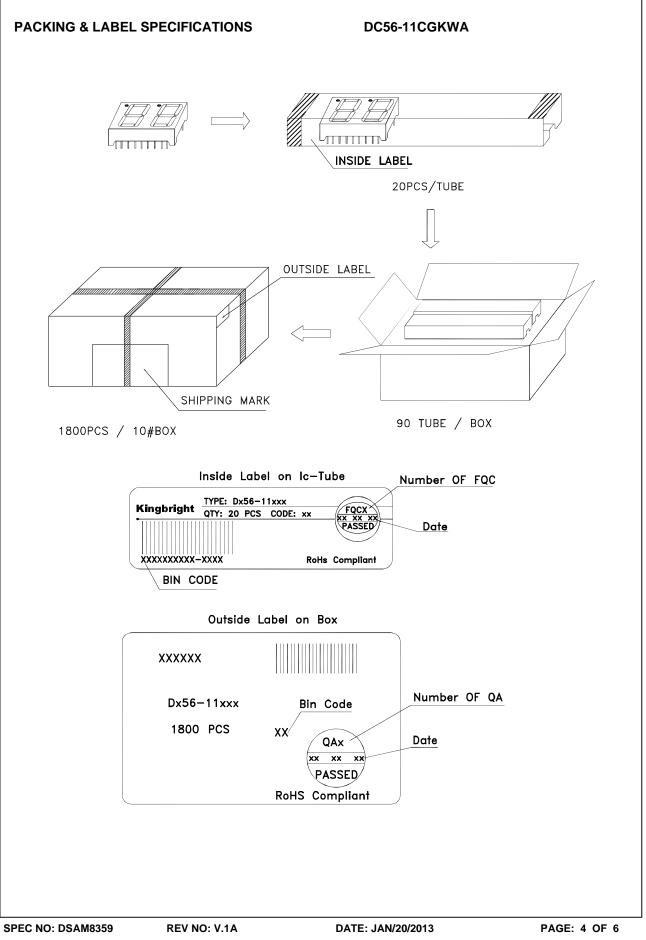
Absolute Maximum Ratings at TA=25°C

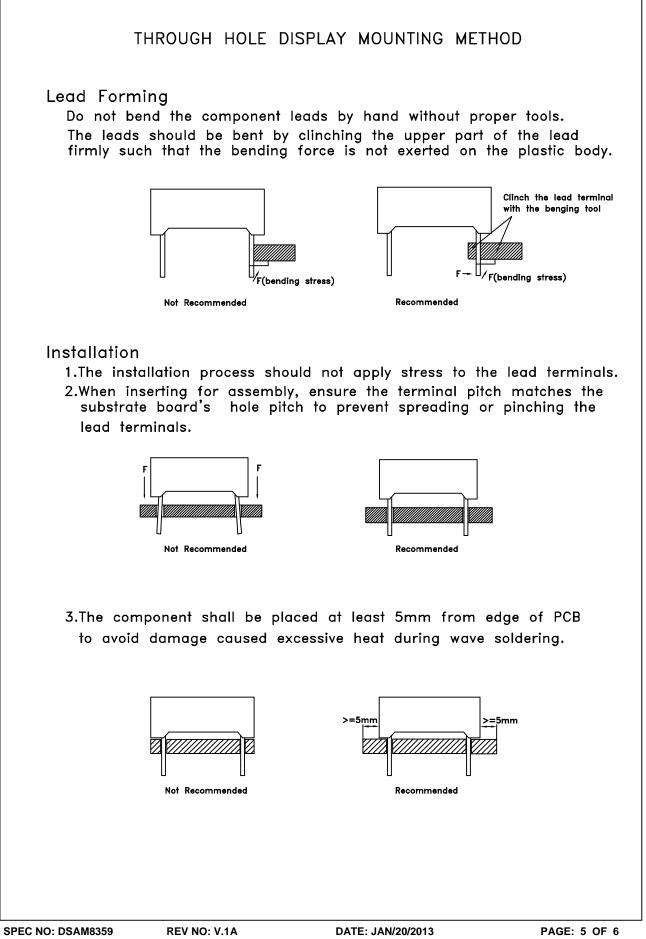
Parameter	Green	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	150	mA		
Reverse Voltage	5	V		
Operating / Storage Temperature	-40°C To +85°C			
Lead Solder Temperature[2]	260°C For 3-5 Seconds			

Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.

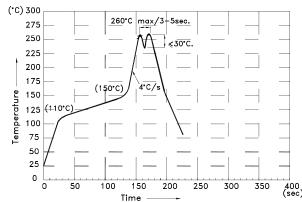






DISPLAY SOLDERING CONDITIONS

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.

2.Do not apply stress on epoxy resins when temperature is over 85°C.

3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy). 4.During wave soldering , the PCB top-surface temperature should be kept below 105°C

5.No more than once.

Soldering General Notes:

- 1. Through-hole displays are incompatible with reflow soldering.
- 2. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

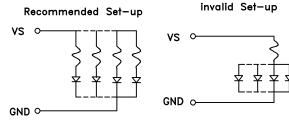
CLEANING

1.Mild "no-clean" fluxes are recommended for use in soldering.

2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning, because they may damage the plastic parts .And the devices should not be washed for more than one minute.

CIRCUIT DESIGN NOTES

 Protective current-limiting resistors may be necessary to operate the Displays.
LEDs mounted in parallel should each be placed in series with its own current-limiting resistor.



All design applications should refer to Kingbright application notes available at http://www.KingbrightUSA.com/ApplicationNotes

DATE: JAN/20/2013 DRAWN: Y.Liu PAGE: 6 OF 6 ERP: 1302000721